



Material Content Data Sheet



Sales Product Name		BTS721L1		Issued		24. January 2018		
MA#		MA001205976						
Package		PG-DSO-20-59		Weight*		499.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.030	2.81	2.81	28062	28062
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		85	
	non noble metal	zinc	7440-66-6	0.169	0.03		339	
	non noble metal	iron	7439-89-6	3.388	0.68		6777	
wire	non noble metal	copper	7440-50-8	137.580	27.52	28.24	275187	282388
	noble metal	gold	7440-57-5	1.516	0.30	0.30	3032	3032
	encapsulation	organic material	carbon black	1333-86-4	0.667	0.13		1335
encapsulation	plastics	epoxy resin	-	30.704	6.14		61414	
	inorganic material	silicondioxide	60676-86-0	302.370	60.48	66.75	604797	667546
leadfinish	non noble metal	tin	7440-31-5	2.746	0.55	0.55	5492	5492
plating	noble metal	silver	7440-22-4	3.476	0.70	0.70	6954	6954
glue	plastics	epoxy resin	-	0.571	0.11		1142	
	noble metal	silver	7440-22-4	2.692	0.54	0.65	5384	6526
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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